

HIGH CTR, AC INPUT RESPONSE TYPE 4 PIN ULTRA SMALL PACKAGE FLAT LEAD OPTOCOUPLER

PS2915-1

FEATURES

- **ULTRA SMALL FLAT-LEAD PACKAGE:**
4.6 (L) x 2.5 (W) x 2.1 (H) mm
- **HIGH CURRENT TRANSFER RATIO:**
CTR = 200% TYP @ $I_F = \pm 1$ mA, $V_{CE} = 5$ V
- **HIGH ISOLATION VOLTAGE**
BV: 2500 V_{r.m.s.}
- **TAPE AND REEL AVAILABLE:**
PS2915-F3, F4: 3500 pcs/reel

DESCRIPTION

The PS2915-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications. An ultra small flat lead package has been provided which realizes a reduction in mounting area of about 30% compared with the PS28XX series.

APPLICATIONS

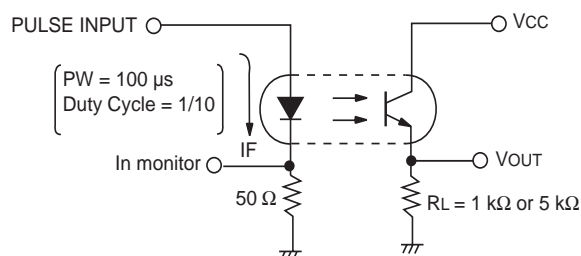
- DC/DC CONVERTER
- MODEM/PC CARD

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

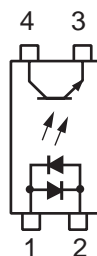
PART NUMBER			PS2915-1		
SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
Diode	V _F	Forward Voltage, I _F = ±1 mA	V	0.9	1.3
	C _T	Terminal Capacitance, V = 0, f = 1.0 MHz	pF	30	
Transistor	I _{CEO}	Collector to Emitter Dark Current, I _F = 0 mA, V _{CE} = 40 V	nA		100
Coupled	CTR	Current Transfer Ratio (I _C /I _F) ¹ , I _F = ±1 mA, V _{CE} = 5 V	%	100	400
	V _{CE(sat)}	Collector Saturation Voltage, I _F = ±1 mA, I _C = 0.2 mA	V	0.13	0.3
	R _{I-O}	Isolation Resistance, V _{I-O} = 1.0 kV _{DC}	Ω	10 ¹¹	
	C _{I-O}	Isolation Capacitance, V = 0 V, f = 1.0 MHz	pF	0.4	
	t _r	Rise Time ² , V _{CC} = 5 V, I _C = 2 mA, R _L = 1 kΩ	μs	5	
	t _f	Fall Time ² , V _{CC} = 5 V, I _C = 2 mA, R _L = 1 kΩ	μs	10	
	t _{on}	On Time, V _{CC} = 5 V, I _F = ±1 mA, R _L = 5 kΩ	μs	40	
	t _{off}	Storage Time ² , V _{CC} = 5 V, I _F = ±1 mA, R _L = 5 kΩ	μs	10	
	t _{off}	Off Time ² , V _{CC} = 5 V, I _F = ±1 mA, R _L = 5 kΩ	μs	120	

Notes:

1. CTR RANK:
N: 100 to 400 (%)
2. Test Circuit for Switching Time



PS2915-1



ABSOLUTE MAXIMUM RATINGS¹ (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
Diode			
IF	Forward Current	mA	±50
ΔIF/°C	Forward Current Derating	mW/°C	0.5
IF (Peak)	Peak Forward Current ²	A	±0.5
PD	Power Dissipation	mW	60
Transistor			
VCEO	Collector to Emitter Voltage	V	40
VECO	Emitter to Collector Voltage	V	5
IC	Collector Current	mA	40
ΔPC/°C	Power Dissipation Derating	mW/°C	1.2
PC	Power Dissipation	mW	120
Coupled			
BV	Isolation Voltage ³	Vr.m.s.	2500
PT	Total Power Dissipation	mW	160
TA	Operating Ambient Temp.	°C	-55 to +100
TSTG	Storage Temperature	°C	-55 to +150

Notes:

1. Operation in excess of any one of these parameters may result in permanent damage.
2. PW = 100 μs, Duty Cycle = 1%.
3. AC voltage for 1 minute at TA = 25 °C, RH = 60 % between input and output.

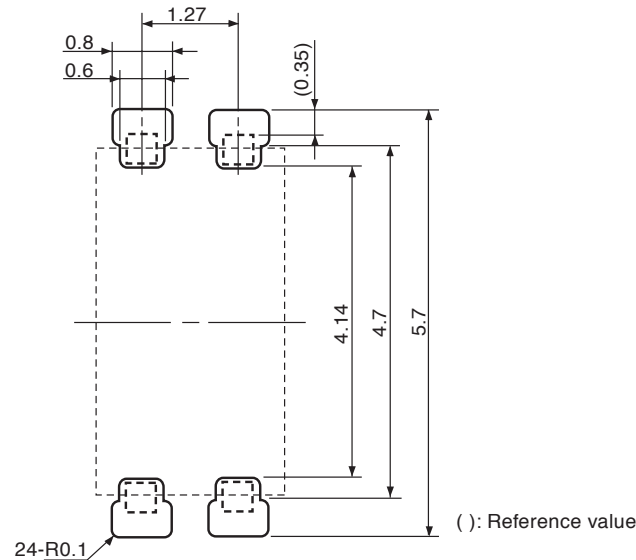
CAUTIONS REGARDING NOISE:

Be aware that when voltage is applied suddenly between the optocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

ORDERING INFORMATION

PART NUMBER	PACKING STYLE
PS2915-1-F3	Embossed Tape 3500 pcs/reel
PS2915-1-F4	

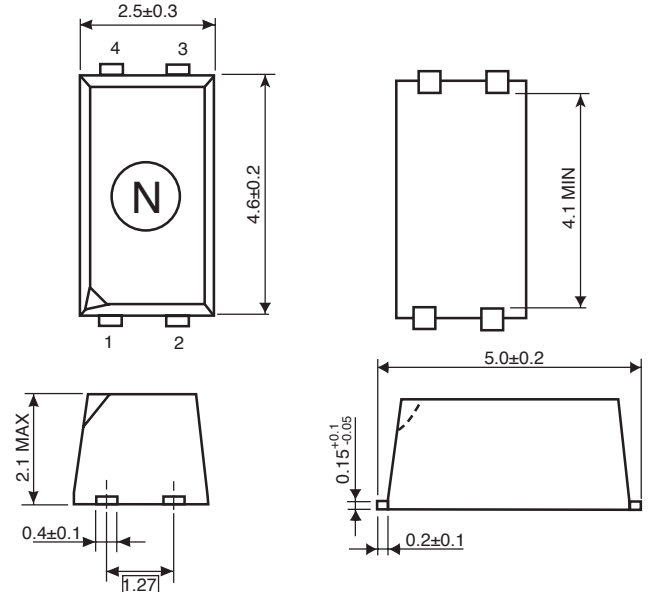
RECOMMENDED MOUNT PAD DIMENSIONS (Units in mm)



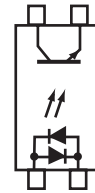
OPTOCOUPLER CONSTRUCTION

PARAMETER	UNITS (MIN)
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

OUTLINE DIMENSIONS (Units in mm)

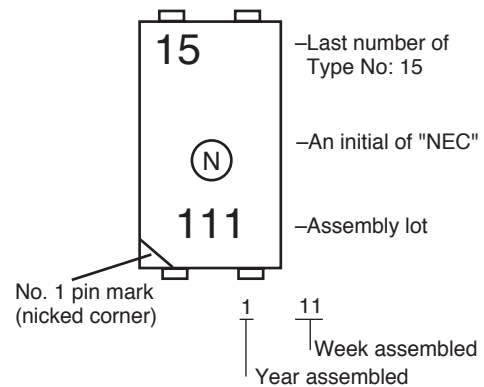


TOP VIEW

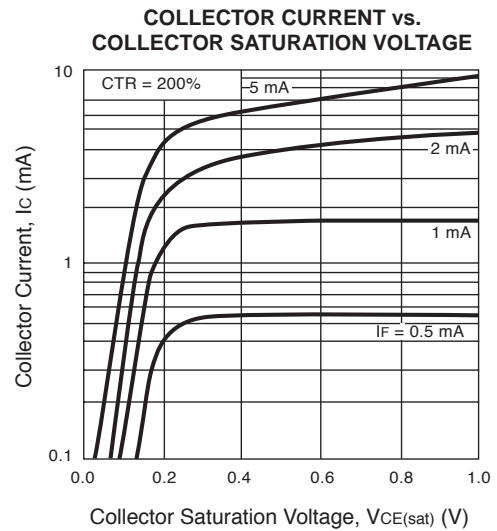
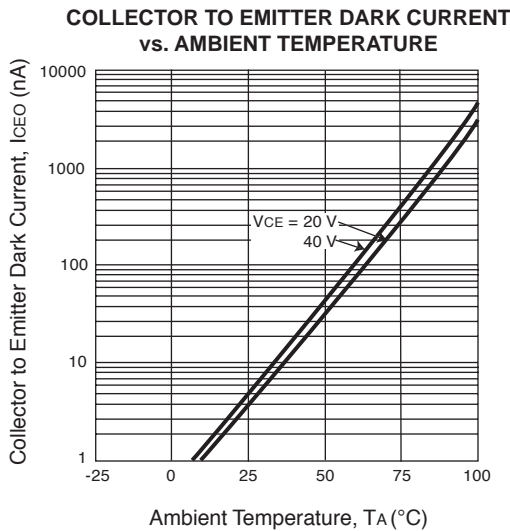
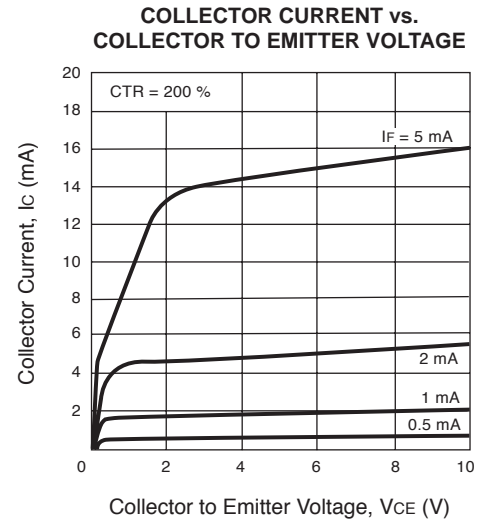
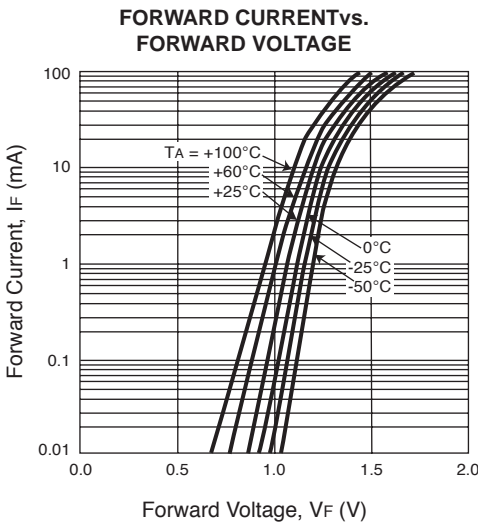
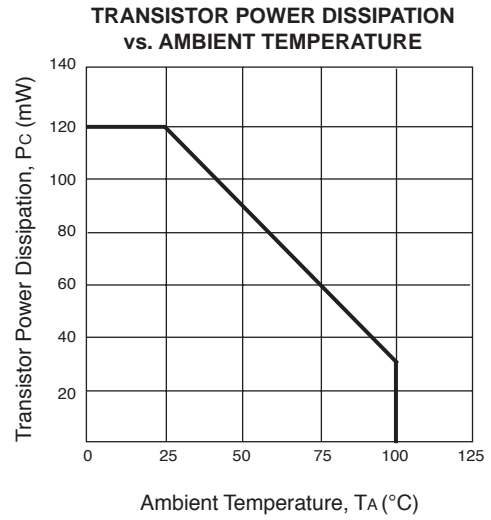
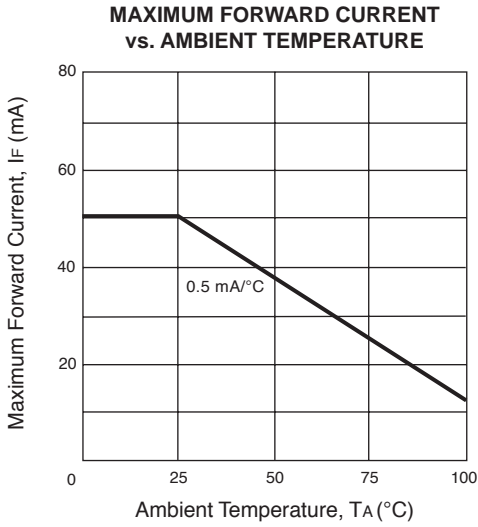


1. Anode, Cathode
2. Cathode, Anode
3. Emitter
4. Collector

MARKING

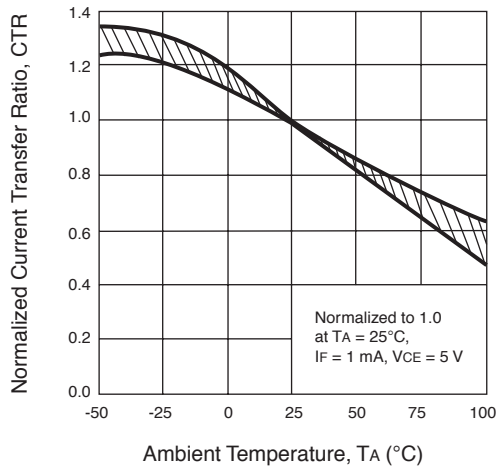


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

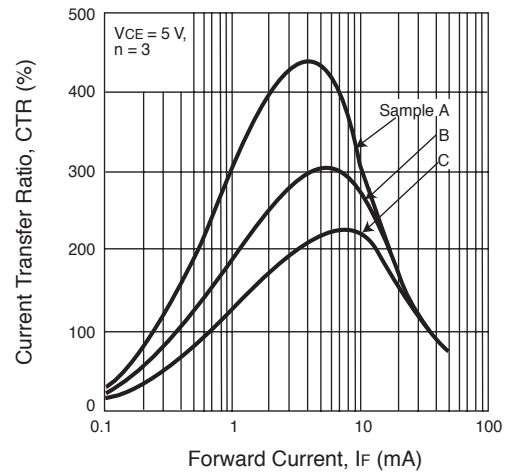


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

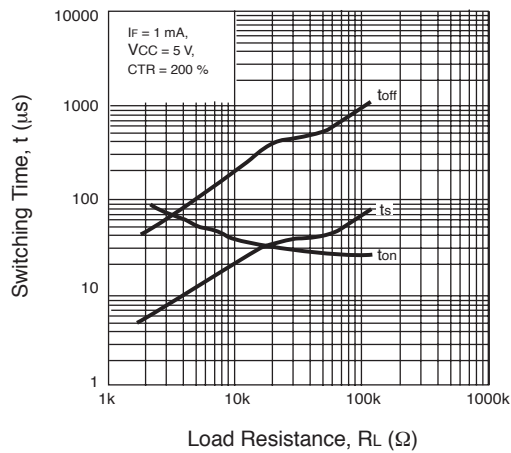
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



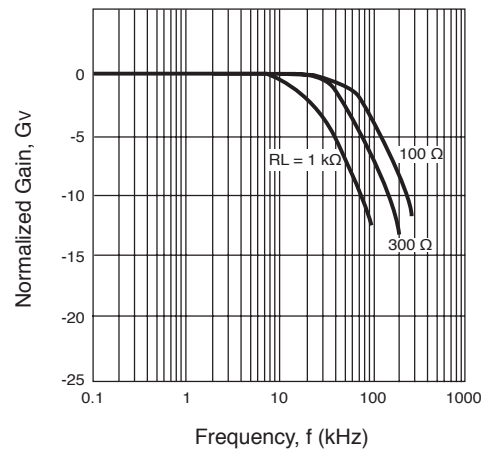
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



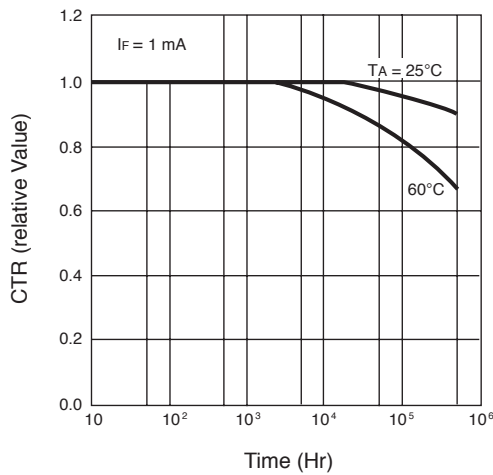
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



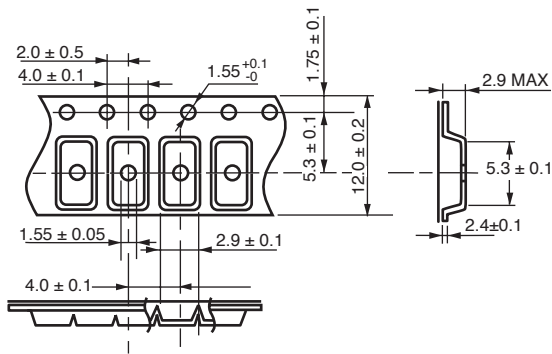
LONG TERM CTR DEGRADATION



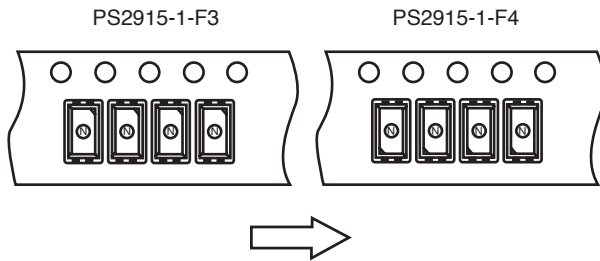
Remark: The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (Units in mm)

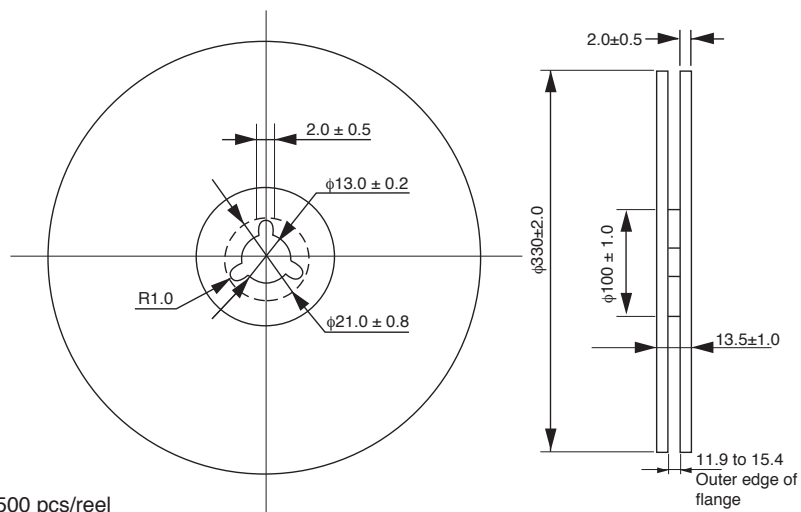
Tape Outline and Dimensions



Tape Direction



Reel Outline and Dimensions



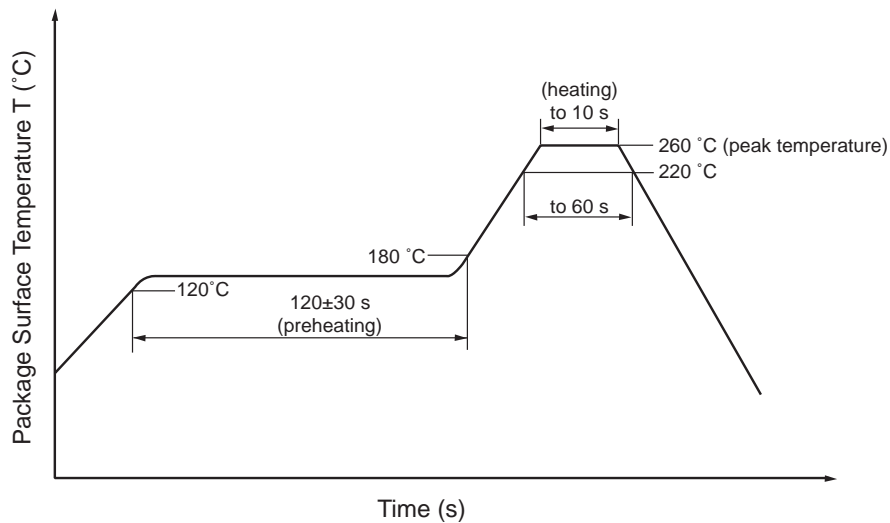
Packing: 3500 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260 °C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220 °C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended).

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended).

(3) Cautions

- Fluxes Avoid removing the residual flux with chlorine-based cleaning solvent after a reflow process.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

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